

Fairchild Semiconductor Product Package Material Disclosure

Package Type	DO-35					
Weight of Package (grams)	Maximum	0.111				
	Mininum	0.109				
Component	Material	Weight in grams	Substance in material	Wt% in finished product min	Wt% in finished product max	CAS#
Studleads CCS Wire	Fe, Cu cladded	0.074-0.076	Fe/Cu Alloy	67%	69%	7439-89-6/ 7440-50-8
Studleads Dumet Wire	Fe /Ni/ Cu Alloy(Trace Element)	0.007-0.010	Fe /Ni/ Cu Alloy(Trace Element)	6%	9%	7439-89-6/ 7440-02-0/ 7440-50-8
Glass Sleeves	PbO/ SiO ₂ / K ₂ O/ B2O3 Alloy(Trace Element)	0.0235-0.0237	PbO/ SiO ₂ / K ₂ O/ B2O3 Alloy(Trace Element)	21.36%	21.55%	1317-36-8/ 7631-86-9/ 12136-45-7 1303-86-2
Plating	Pure Tin	0.002625-0.002627	Sn	2.39%	2.39%	7440-31-5
Marking Ink	Carbon Black/ Formaldehyde /Phenol/ Triethylene glycol/ monomethyl ether	0.00003	Carbon Black/ Formaldehy de /Phenol/ Triethylene glycol/ monomethyl ether	0.0027%	0.0027%	7440-44-0/ 50-00-0/ 108-95-2/ 112-35-6



Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.